



June 18, 2026

PCN #	Revision	Issue Date	Description
26-01	A	May 18, 2026	Original Release
26-01	B	June 18, 2026	The affected product list has been updated. BGA packages built in ASEM, FPBGA, and FCCSP have been removed from the packages to qualify in ASEK M1. Please refer to the updated affected product list in the "Affected Products" section link.

Subject: UPDATE - PCN#26-01 Notification of Alternate Additional Assembly Qualification for MXO2-MXO3-MXO3D FPGA Products

Overview

Lattice is issuing this Product Change Notification (PCN) regarding our intent of using an alternate assembly source on select Lattice Semiconductor products to improve supply chain flexibility and secure additional capacity. Lattice is now qualifying select MXO2-MXO3-MXO3D CABGA (Chip Array Ball Grid Array) wirebonded packages at Advanced Semiconductor Electronics Kaohsiung (ASEK) M1 in Penang, Malaysia.

There is no change in form, fit, and function on the affected products.

Description

Advanced Semiconductor Electronics M1 is a new factory in Penang, Malaysia opened in Q4'2025 for production, with assembly qualification already in progress across ASEK customers. ASEK M1 will be fully managed and operated by ASE Kaohsiung.

Effects on Customer Design

No change in form, fit and function on listed Lattice devices to be assembled at ASEK M1. There will be no impact on customer designs.

Lattice Semiconductor Home Page: <https://www.latticesemi.com>

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Affected Products

The Ordering Part Numbers (OPNs) affected by this PCN are listed [here](#). This PCN also affects any custom devices (i.e. factory programmed, special test, tape and reel, non-standard speed grade and package, etc.), which are derived from any of the devices listed.

Material Set Changes

All devices undergoing qualification at ASEK M1 will utilize Lattice's standard Bill of Materials (BOM), consistent with the material sets already qualified for current Lattice products. This approach is supported by existing reliability data from products in active production and benefits from Lattice's extensive high-volume manufacturing experience. By maintaining the standard BOM and using ASEK qualified production materials, Lattice ensures continued high quality and manufacturability.

PACKAGE TYPE	CABGA
ASSY SITE	ASEK M1
SUBSTRATE	SAME
MATERIAL SET	SAME
WIRE	SAME
MOLD COMPOUND	SAME
SOLDER BALL	SAME

Table 1. Summary of Materials

Data Sheet Specifications

This PCN has no impact on any data sheet specifications.

Qualification Data

Qualification is in progress, with target completion dates as follows:

Commercial/Industrial Grade: August 8, 2026

After qualification, a qualification report will be available upon request via Zoho ticket [here](#).

Device Identification

Devices manufactured at ASEK M1 can be identified by a character (“8”) in the fifth position of ILF marked on the topside of the devices. This ILF is also marked on the label on the outside of the inventory box as well as on the anti-static moisture barrier bag within. See device topside marking example below:

Example:



5th character in the ILF will be “8” to indicate devices built at Advanced Semiconductor Electronics Kaohsiung M1.

Sample Support

Conversion timing for this PCN is 90 days from the date of this Notice. No action is required (meaning no changes to OPNs, your internal Bills of Material, backlog or orders) unless you plan to do further evaluation.

Should samples be required to complete evaluation of this PCN, they can be ordered now. Samples for this PCN will use the “**ARK**” suffix appended to the standard OPNs as shown in the example below:

Example:

Standard OPN	: LCMXO3D-4300HC-5BG256I
ASEK M1 sample specific OPN	: LCMXO3D 4300HC-5BG256IARK

Implementation Timing Summary

- **Sample Request Cut-off Date** : June 18, 2026
- **Effective Date, Commercial/Industrial Grade** : August 18, 2026

Recommended Actions

Please work closely with your normal Lattice Sales contact to provide further clarification on your sample needs.

Customers who have further questions regarding this specification change are encouraged to contact local field support or sales@latticesemi.com.

Response

In accordance with J-STD-46, this change is deemed accepted by the customer if no acknowledgement is received within 30 days from this Notice. Lattice PCNs are available on the [Lattice PCN web page](#). Please sign up to receive e-mail PCN alerts by registering [here](#). If you already have a Lattice web account and wish to receive PCN alerts, you can do so by logging into [your account](#) and making edits to your subscription options.

Sincerely,

Lattice PCN Administrator